

30V P-Channel Trench MOSFET(Preliminary)

General Description

- Trench Power technology
- Low R_{DS(ON)}
- Low Gate Charge&
- Optimized for fast-switching applications

Applications

- Synchronous Rectification in DC/DC and AC/DC Converters
- Isolated DC/DC Converters in Telecom and Industrial

Product Summary

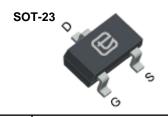
 V_{DS} -30V

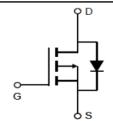
 $I_{D} \ (at \ V_{GS} = -10V) \qquad \qquad -4A$ $R_{DS(ON)} \ (at \ V_{GS} = -10V) \qquad \qquad < 52m\Omega$

 $R_{DS(ON)}$ (at V_{GS} =-4.5V) < 60m Ω

 $R_{DS(ON)}$ (at V_{GS} =-2.5V) < $85m\Omega$







Part Number	Package Type	Form	Marking
TTX3401A	SOT-23	Tape & Reel	3401A

Absolute Maximum Ratings (T_A =25°C unless otherwise noted)

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V _{DS}	-30	V
Gate-Source Voltage		V _{GS}	±12	V
Continuous Drain Current B	T _C =25°C	I _D	-4	Δ
	T _C =70°C		-3.3	А
Pulsed Drain Current ^A		I _{DM}	-12	Α
Avalanche Current ^A		I _{AS}	-18	Α
Single Pulse Avalanche Energy L =0.3mH ^A		E _{AS}	48.6	mJ
Power Dissipation ^C	T _C =25°C	- P _D	1.4	W
	T _C =70°C		0.89	W
Junction and Storage Temperature Range		T _J , T _{STG}	-55 to 150	°C
Thermal Characteristics				

Thermal Characteristics

Parameter		Symbol	Maximum	Units		
Maximum Junction-to-Lead	Steady-State	$R_{\Theta JL}$	90	00.00		
Maximum Junction-to-Ambient	Steady-State	$R_{\Theta JA}$	100	°C/W		



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Symbol Parameter		Conditions		Min	Тур	Max	Units
STATIC P	ARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$		-30			V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{po} = -30 \text{V}, V_{po} = 0 \text{V}$	T _J =25°C T _J =125°C			-1 -100	μA
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 12V$	11 - 120 0			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$		-0.6	-0.9	-1.2	V
		V _{GS} =-10V, I _D =-2A			43	52	mΩ
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-4.5V, I _D =-2A			50	60	mΩ
		V _{GS} =-2.5V, I _D =-1.5A			65	85	mΩ
g _{FS}	Forward Transconductance	V_{DS} =-5V, I_{D} =-4A			9		S
V_{SD}	Diode Forward Voltage	I _S =-2A, V _{GS} =0V				-1	V
I _s	Maximum Body-Diode Continuous Current B					-4	А
DYNAMIC	PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-15V, f =1MH _Z			903		
C _{oss}	Output Capacitance				70		pF
C _{rss}	Reverse Transfer Capacitance				63		
R_g	Gate Resistance	f =1MH _Z			5.5		Ω
SWITCHIN	NG PARAMETERS						
Q _g (10V)	Total Gate Charge				17.1		
Q _g (4.5V)	Total Gate Charge	\/ - 10\/\/ - 15\/	1 – 40		8.2		nC
Q_{gs}	Gate Source Charge	$V_{GS} = -10V, V_{DS} = -15V, I_{D} = -4A$			1.8		IIC
Q_{gd}	Gate Drain Charge				2		
t _{D(on)}	Turn-On Delay Time	V_{GS} =-10V, V_{DS} =-15V, I_{D} =-4A, R_{G} =2.5 Ω			6.2		
t _r	Turn-On Rise Time				3.2		ns
t _{D(off)}	Turn-Off Delay Time				36		
t _f	Turn-Off Fall Time				8.8		
t _{rr}	Body Diode Reverse Recovery Time				12		ns
Q _{rr}	Body Diode Reverse Recovery Charge				3.8		nC

- A. Single pulse width limited by maximum junction temperature.
- B. The maximum current rating is package limited.
- C. The power dissipation P_D is based on $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

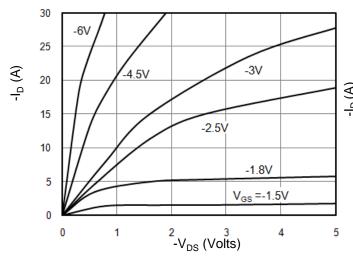


Figure 1: On-Region Characteristics

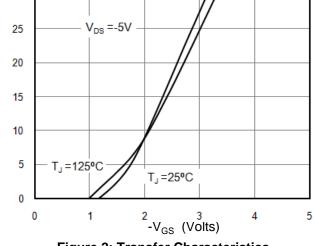


Figure 2: Transfer Characteristics

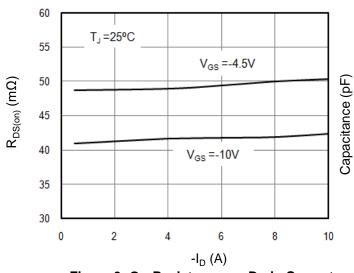


Figure 3: On-Resistance vs. Drain Current

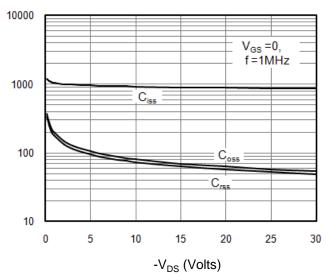


Figure 4: Capacitance Characteristics

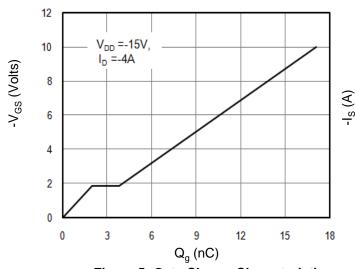


Figure 5: Gate Charge Characteristics

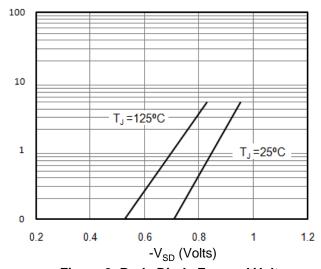


Figure 6: Body Diode Forward Voltage



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

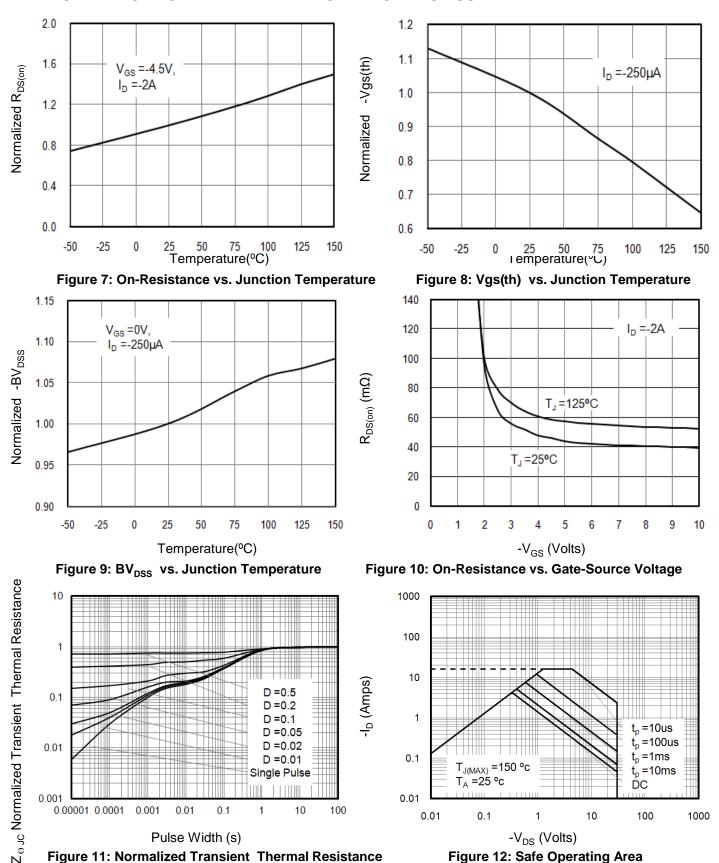


Figure A: Gate Charge Test Circuit and Waveform

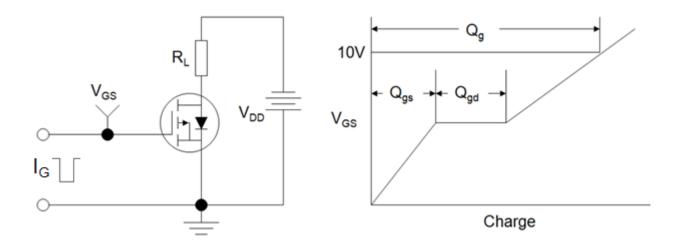


Figure B: Resistive Switching Test Circuit and Waveform

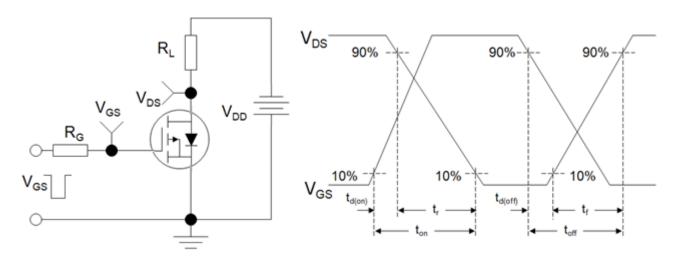
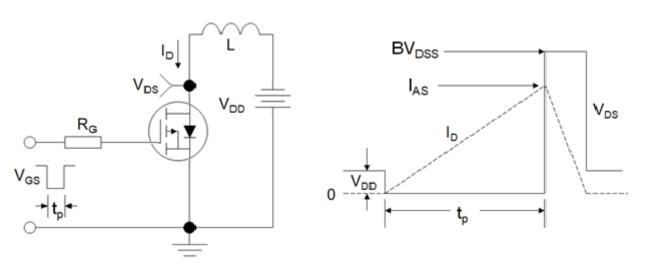
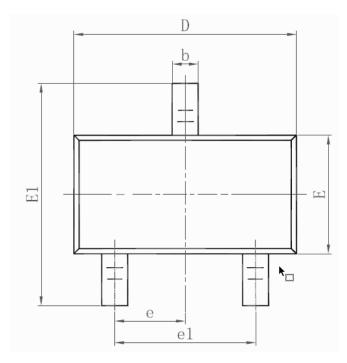


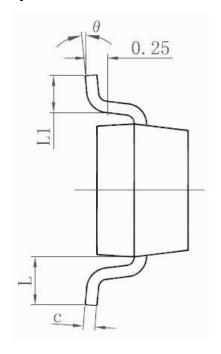
Figure C: Unclamped Inductive Switching Test Circuit and Waveform

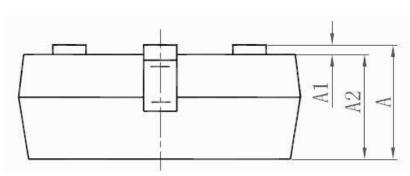




SOT-23(长电)



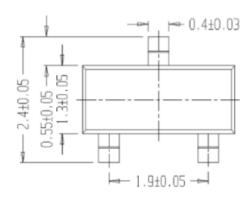


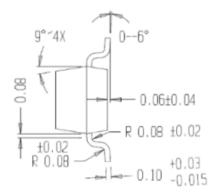


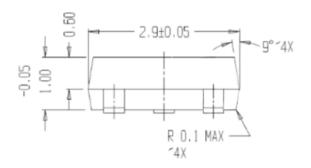
Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
Е	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP.		0.037 TYP.		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF.		0.022 REF.		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

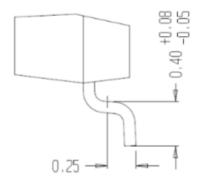


SOT-23(友润)



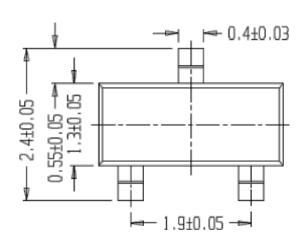


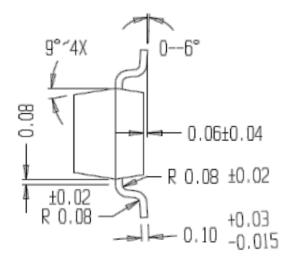


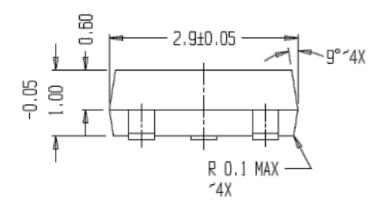


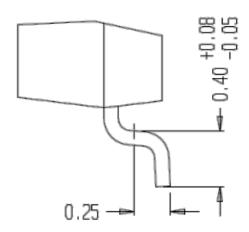


SOT-23(集佳)











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